

WHAT IS CLAIMED IS:

1. A semiconductor laser device, comprising:
a first lead portion having a mounting portion on which a
semiconductor laser chip is mounted;
a second lead portion for an electrode; and
a resin portion fixing said first and second lead portions;
said second lead portion being provided with an engagement portion
engaging with said resin portion in a longitudinal direction of said second
lead portion, and extending straight within said resin portion.

2. The semiconductor laser device according to claim 1, wherein
said engagement portion includes a wide portion formed by locally
expanding a width of said second lead portion within said resin portion.

3. The semiconductor laser device according to claim 1, comprising:
a third lead portion for heat radiation extending on a same side as
said second lead portion from said resin portion.

4. The semiconductor laser device according to claim 1, wherein an
outer circumference of said resin portion has a circular shape with said
semiconductor laser chip arranged at a center.

5. The semiconductor laser device according to claim 1, wherein
said resin portion has a window portion through which light emitted from
said semiconductor laser chip passes.

6. The semiconductor laser device according to claim 1, wherein an
outer circumference of said resin portion is provided with a cut portion for
stopping rotation.

7. The semiconductor laser device according to claim 1, wherein
said mounting portion in said first lead portion is made wider than said

first lead portion excluding said mounting portion.

- 5 8. A semiconductor laser device, comprising:
a first lead portion having a mounting portion on which a semiconductor laser chip is mounted;
a second lead portion for an electrode;
a third lead portion for heat radiation; and
a resin portion fixing said first, second and third lead portions;
said second and third lead portions extend on a same side from said resin portion.